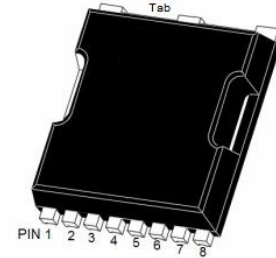


■ PRODUCT CHARACTERISTICS

| | |
|-----------------------------------|-------|
| VDSS | 120V |
| $R_{DS(on)}$ Typ($V_{GS}@=10V$) | 4.5mΩ |
| ID | 250A |

■ FEATURES

Surface-mounted package Advanced trench cell design Super trench

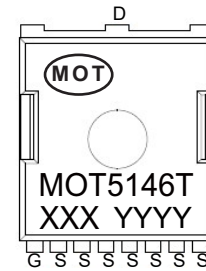


TOLL-8L

■ APPLICATIONS

High power system inverter
Light electric vehicles
BMS
Drones

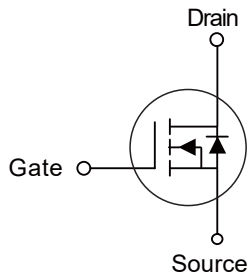
Pin configuration (Top view)



XXX = Lot Number
YYYY = Year Week

Marking

■ SYMBOL



Order information

| Device | Package | Shipping |
|-------------|---------|----------------|
| MOT5146T/TR | TOLL-8L | 4000/Tape&Reel |

■ ABSOLUTE MAXIMUM RATINGS ($T_C = 25^\circ\text{C}$ unless otherwise noted)

| Parameter | Symbol | Conditions | Min | Max | Unit |
|---|-----------------|---|-----|----------|--------------------|
| Drain-Source Voltage | V_{DS} | $T_C = 25^\circ\text{C}$ | 120 | - | V |
| Gate-Source Voltage | V_{GS} | $T_C = 25^\circ\text{C}$ | - | ± 20 | V |
| Drain Current (DC) * | I_D | $T_C = 25^\circ\text{C}, V_{GS} = 10\text{ V}$ | - | 250 | A |
| | | $T_C = 100^\circ\text{C}, V_{GS} = 10\text{ V}$ | - | 177 | A |
| Drain Current (Pulsed) *** | I_{DM} | $T_C = 25^\circ\text{C}, V_{GS} = 10\text{ V}$ | - | 396 | A |
| Drain power dissipation | P_{tot} | $T_C = 25^\circ\text{C}$ | - | 375 | W |
| Storage Temperature | T_{stg} | | -55 | 175 | $^\circ\text{C}$ |
| Junction Temperature | T_J | | - | 175 | $^\circ\text{C}$ |
| Continuous-Source Current | I_S | $T_C = 25^\circ\text{C}$ | - | 250 | A |
| Single Pulsed Avalanche Energy | E_{AS} | $V_{DD} = 50\text{ V}, L = 1.0\text{ mH}$ | - | 922 | mJ |
| Thermal Resistance- Junction to Ambient** | $R_{\theta JA}$ | | - | 40 | $^\circ\text{C/W}$ |
| Thermal Resistance- Junction to Case** | $R_{\theta JC}$ | | - | 0.45 | |

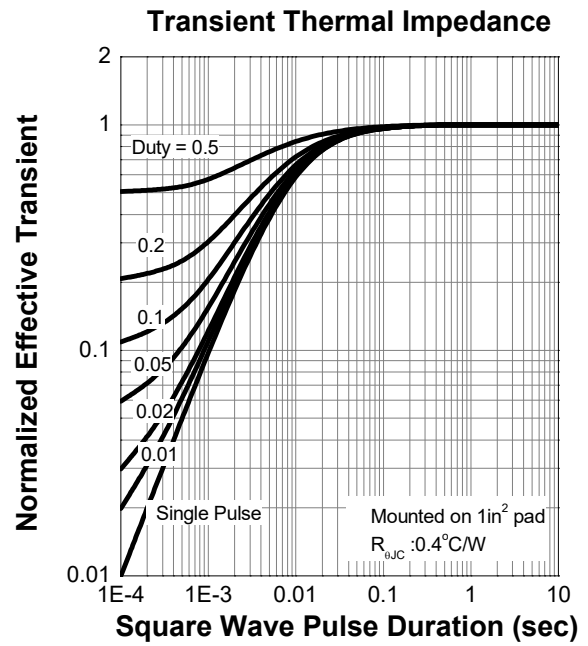
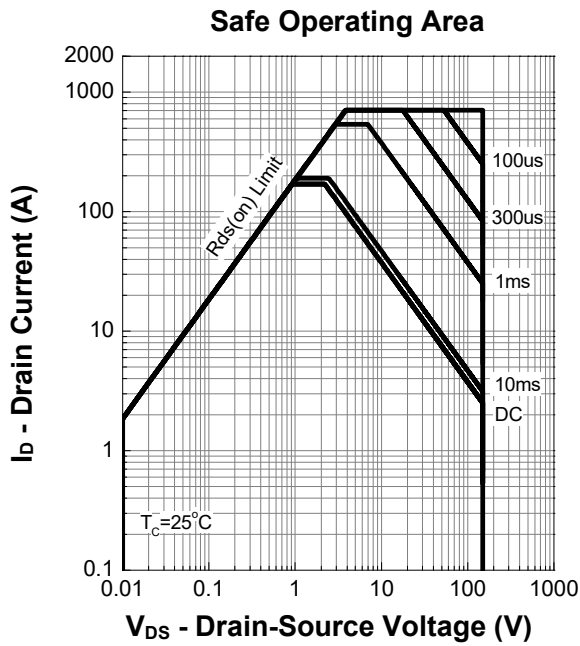
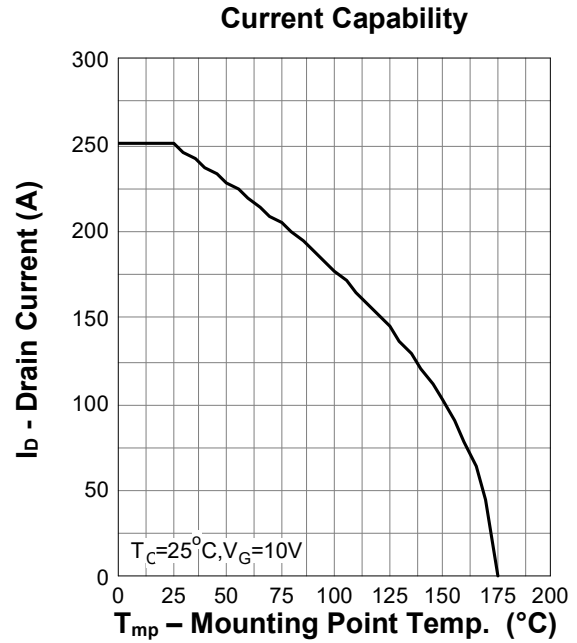
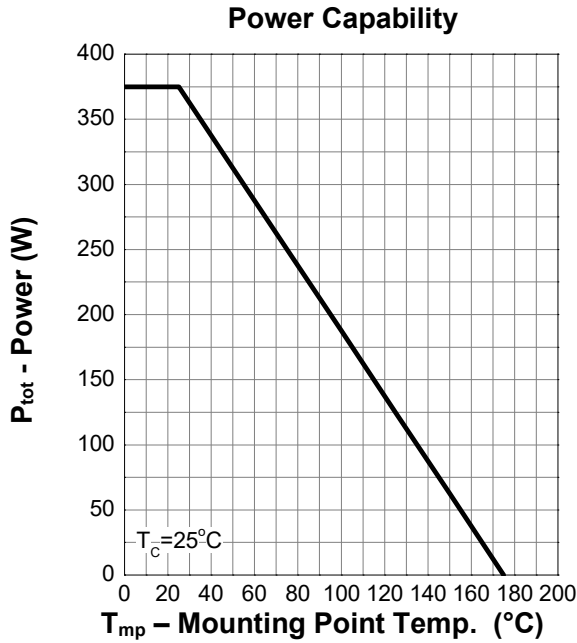
■ ELECTRICAL CHARACTERISTICS ($T_C = 25^\circ\text{C}$, unless otherwise specified)

| Parameter | Symbol | Conditions | Min | Typ | Max | Unit |
|---|--------------|---|-----|------|-----------|---------------|
| Static Characteristics | | | | | | |
| Drain-Source Breakdown Voltage | BV_{DSS} | $V_{GS} = 0\text{ V}, I_{DS} = 250\ \mu\text{A}$ | 120 | - | - | V |
| Gate Threshold Voltage | $V_{GS(th)}$ | $V_{DS} = V_{GS}, I_{DS} = 250\ \mu\text{A}$ | 2 | - | 4 | V |
| Drain Leakage Current | I_{DSS} | $V_{DS} = 96\text{ V}, V_{GS} = 0\text{ V}$ | - | - | 1 | μA |
| Gate Leakage Current | I_{GSS} | $V_{GS} = 0\text{ V}, V_{GS} = \pm 20\text{ V}$ | - | - | ± 100 | nA |
| On-State Resistance ^a | $R_{DS(ON)}$ | $V_{GS} = 10\text{ V}, I_{DS} = 20\text{ A}$ | - | 4.5 | 5.5 | m Ω |
| | | $V_{GS} = 6\text{ V}, I_{DS} = 10\text{ A}$ | - | 6.5 | 7.5 | |
| Diode Characteristics | | | | | | |
| Diode Forward Voltage ^a | V_{SD} | $I_{SD} = 20\text{ A}, V_{GS} = 0\text{ V}$ | - | - | 1.3 | V |
| Reverse Recovery Time | t_{rr} | $I_{DS} = 20\text{ A}, V_{GS} = 0\text{ V}$ $di_{SD}/dt = 100\text{ A}/\mu\text{s}$ | - | 92 | - | nS |
| Reverse Recovery Charge | Q_{rr} | | - | 337 | - | nC |
| Dynamic Characteristics | | | | | | |
| Input Capacitance | C_{iss} | $V_{GS} = 0\text{ V}, V_{DS} = 60\text{ V}$ Frequency = 1 MHz | - | 4779 | - | pF |
| Output Capacitance | C_{oss} | | - | 570 | - | |
| Reverse Transfer Capacitance ^b | C_{riss} | | - | 34 | - | |
| Turn-on Delay Time | $t_d(on)$ | $V_{DS} = 60\text{ V}, V_{GEN} = 10\text{ V},$ $R_G = 3.9\ \Omega, R_L = 3\ \Omega,$ $I_{DS} = 20\text{ A}$ | - | 16 | - | nS |
| Turn-on Rise | t_r | | - | 27 | - | |
| Turn-off Delay Time | $t_d(off)$ | | - | 51 | - | |
| Turn-off Fall Time | t_f | | - | 27 | - | |
| Gate Charge Characteristics ^b | | | | | | |
| Total Gate Charge | Q_g | $V_{DS} = 60\text{ V}, V_{GS} = 10\text{ V},$ $I_{DS} = 20\text{ A}$ | - | 80 | - | nC |
| Gate-Source Charge | Q_{gs} | | - | 24 | - | |
| Gate-Drain Charge | Q_{gd} | | - | 18 | - | |

Notes :

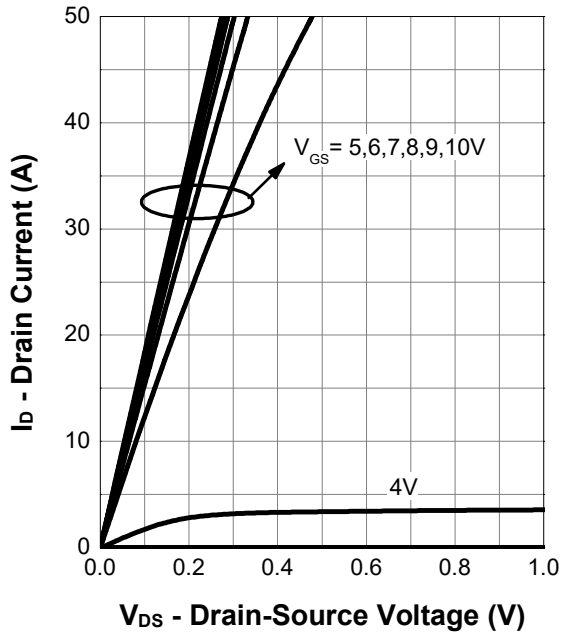
- * Pulse width $\leq 300\ \mu\text{s}$, duty cycle $\leq 2\%$
- ** Surface Mounted on minimum footprint pad area.
- *** Limited by bonding wire
- a : Pulse test ; pulse width $\leq 300\ \mu\text{s}$, duty cycle $\leq 2\%$
- b : Guaranteed by design, not subject to production testing

■ TYPICAL CHARACTERISTICS

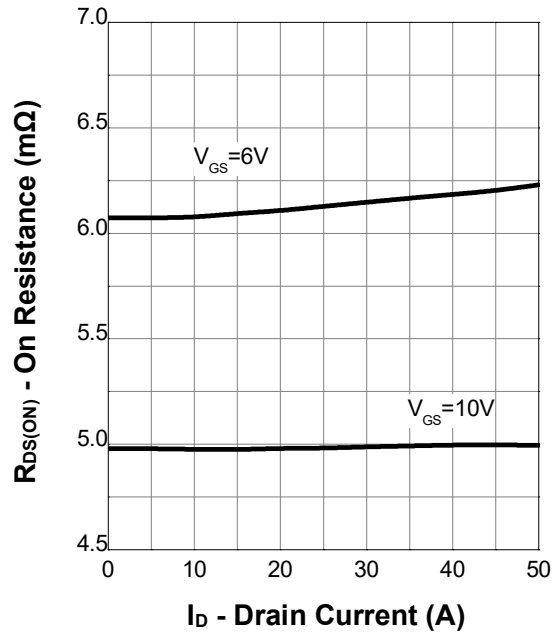


■ TYPICAL CHARACTERISTICS(Cont.)

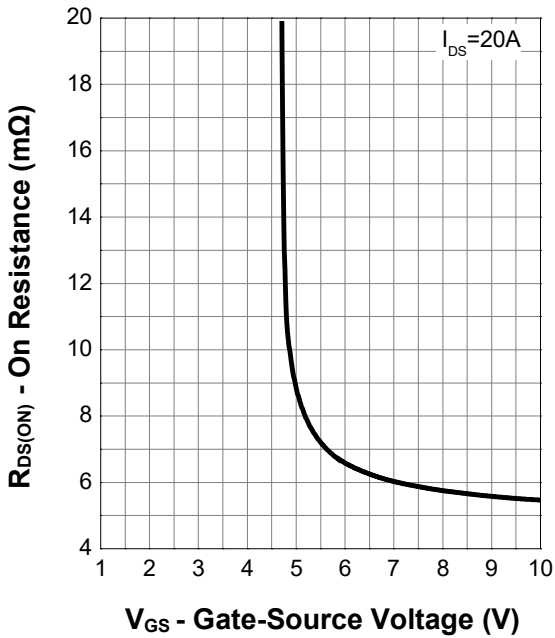
Output Characteristics



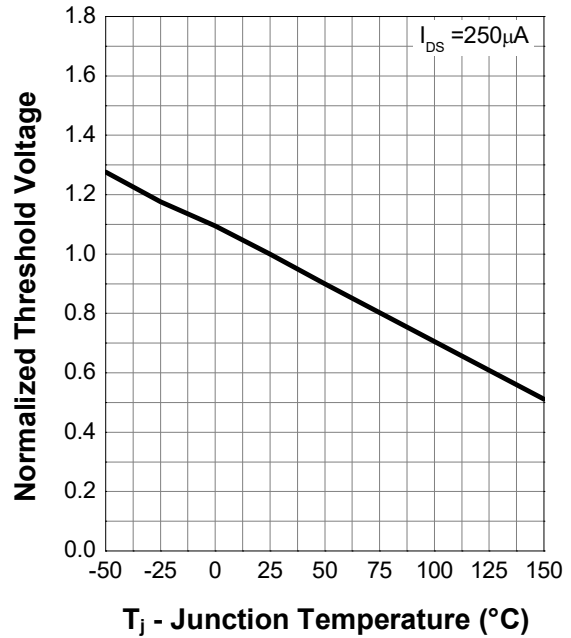
On Resistance



Transfer Characteristics

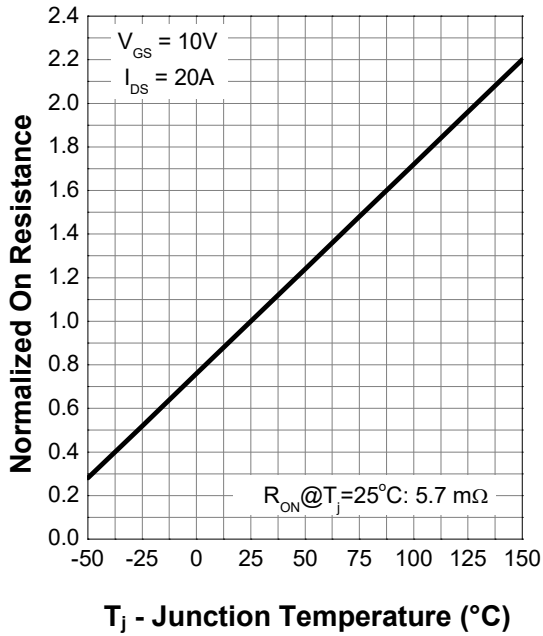


Normalized Threshold Voltage

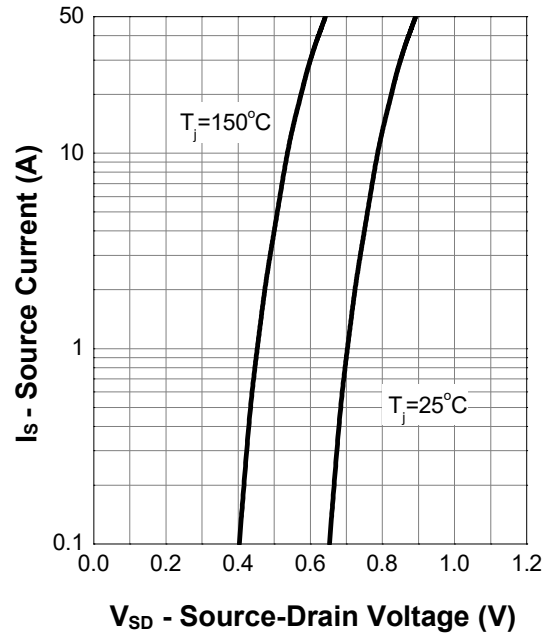


■ TYPICAL CHARACTERISTICS(Cont.)

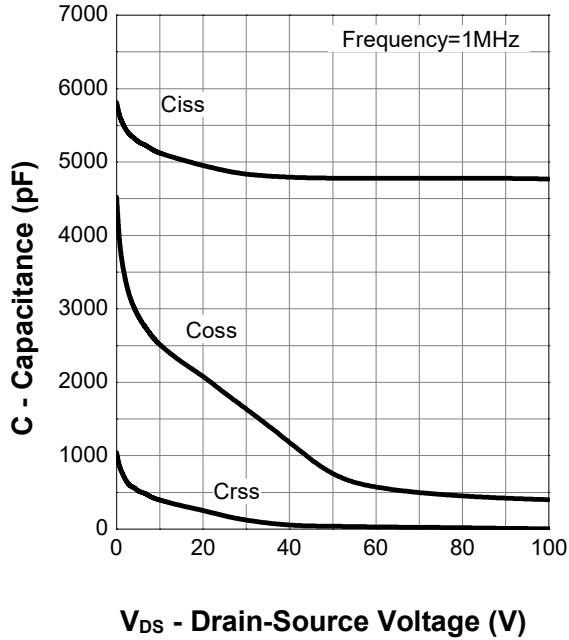
Normalized On Resistance



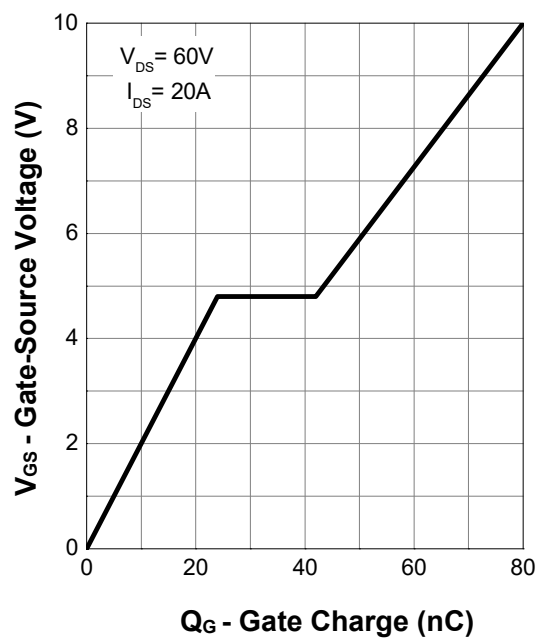
Diode Forward Current



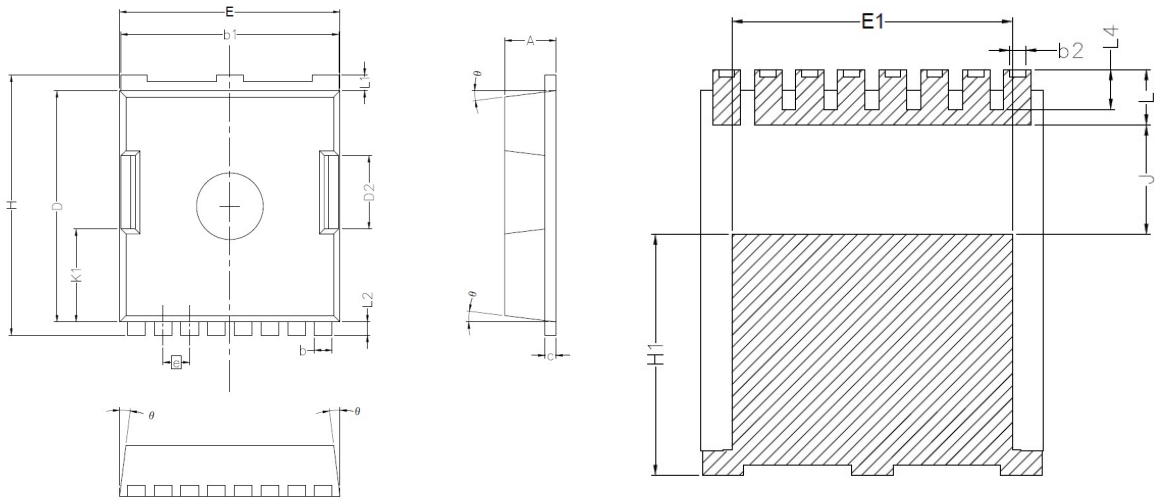
Capacitance



Gate Charge



■ TOLL-8L PACKAGE OUTLINE DIMENSIONS



| Symbol | Dimensions In Millimeters | |
|--------|---------------------------|-------|
| | Min. | Max. |
| A | 2.20 | 2.40 |
| b | 0.70 | 0.90 |
| b1 | 9.70 | 9.90 |
| b2 | 0.42 | 0.50 |
| c | 0.40 | 0.60 |
| D | 10.28 | 10.58 |
| D2 | 3.10 | 3.50 |
| E | 9.70 | 10.10 |
| E1 | 7.90 | 8.30 |
| e | 1.20BSC | |
| H | 11.48 | 11.88 |
| H1 | 6.75 | 7.15 |
| N | 8 | |
| J | 3.00 | 3.30 |
| K1 | 3.98 | 4.38 |
| L | 1.40 | 1.80 |
| L1 | 0.60 | 0.80 |
| L2 | 0.50 | 0.70 |
| L4 | 1.00 | 1.30 |
| θ | 4° | 10° |

- The information contained hSurface-mounted package Advnced terch cell design Super trencherein is subject to change without notice.
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